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Aehr Test Systems Receives Follow-on Orders for FOX-XP™ Test and Burn-in Solution

Fremont, CA (September 28, 2017) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced that it has received follow-on orders totaling \$2.7 million from a subcontractor of its initial lead FOX-XP™ Test and Burn-in System customer. The orders include a partially populated FOX-XP system, multiple DiePak® Carriers for their next generation devices and multiple FOX DiePak Loader/Unloaders to increase their current production capacity.

Gayn Erickson, President and CEO of Aehr Test Systems, commented, “We are excited to receive these additional follow-on orders from this large multinational customer for their production test/burn-in requirements. The new orders build on an existing device test/burn-in implementation at this customer now moving into volume production, which continues to expand our production presence for multiple generations of devices.

“The FOX-XP system’s unique capability to deliver thousands of test resources to each DiePak Carrier loaded in the FOX-XP system makes it appropriate for volume test/burn-in production of high power small footprint devices such as those being produced by this customer. In addition, the system is capable of heating or cooling devices while in test/burn-in using a proprietary design, which can handle up to 2 kW of heat energy per DiePak Carrier to ensure that each device’s desired junction temperature is maintained very accurately. Another advantage of the FOX-XP system design is the integrated autoloader option, which handles device loading/unloading of the DiePak Carrier in high volume production.

“We believe that the FOX-XP system’s capabilities and our cost-effectiveness for high volume singulated device test/burn-in differentiate Aehr Test from the competition and enable us to address our customer’s current and next generation devices requirements”

The FOX-XP system, available with multiple WaferPak™ Contactors (full wafer test) or multiple DiePak Carriers (singulated die/module test) configurations, is capable of functional test and burn-in/cycling of integrated optical devices, 2D and 3D sensors, magnetic sensors, flash memories, microcontrollers, and other leading-edge ICs in either wafer form, before they are assembled into single or multi-die stacked packages, or in singulated die or module form.

A single FOX-XP test system may be configured with up to 18 Blades of wafer test resources, enabling up to 18 wafers to be tested simultaneously handling 1 kW each, or 9 wafers or DiePak

Carriers at up to 2 kW each. Each Blade may be configured with up to eight Channel Modules of test resources. These Channel Modules may be: Universal Channel Channel Modules (UCCMs), High Current Channel Modules (HCCMs), or High Voltage Channel Modules (HVCMS) to supply device stimulus to test/burn-in/cycle die or modules. The footprint of the 18-wafer test system is similar to the footprint of typical semiconductor Automatic Test Equipment (ATE) that can only test one wafer at a time.

The FOX-XP system's FOX WaferPak Contactor provides a cost-effective solution for making full wafer electrical die contact in a multi-wafer environment and may contain up to tens of thousands of probes to contact all die simultaneously on wafers and substrates up to 300mm. The DiePak® Carrier provides a cost-effective solution for making both thermal and electrical singulated die/module test contact in a multi-DiePak Carrier environment and may contain up to thousands of contacts to test/burn-in 100's of devices on a single DiePak Carrier. Other key components of a FOX-XP test cell are the FOX WaferPak Aligner, which provides fully automatic alignment of the customer's wafers to the WaferPak Contactor, and the FOX DiePak Loader/Unloader, which enables fully automatic handling of device exchanges with the DiePak Carriers.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic, optical and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, incremental capacity needs, and new opportunities for Aehr Test products in package, wafer level, and singulated die/module level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX-P™ families of test and burn-in systems, the FOX WaferPak Aligner, the FOX DiePak Loader/Unloader, the FOX WaferPak Contactor, and the FOX DiePak® Carrier. The ABTS system is used in production and qualification testing of packaged parts for lower power and higher power logic devices as well as all common types of memory devices. The FOX-XP™ system is a full wafer contact and singulated die/module test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers, systems-on-a-chip, and integrated optical devices. The WaferPak Contactor contains a unique full wafer probe card capable of testing wafers up to 300mm that enables IC manufacturers to perform test and burn-in of full wafers on Aehr Test FOX systems. The DiePak Carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of both bare die and modules. For more information, please visit Aehr Test System's website at www.aehr.com.

Safe Harbor Statement

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding Aehr Test's expectations, beliefs, intentions or strategies regarding the FOX products, including statements regarding future market opportunities and conditions, expected product shipment dates and customer orders or commitments. These risks and uncertainties include, without limitation, acceptance by customers of the FOX and WaferPak Contactor technologies, acceptance by customers of the FOX-XP system, WaferPak Aligners, DiePak Loader/Unloaders, WaferPak Contactors and DiePak Carriers shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described, as well as general market conditions, customer demand and acceptance of Aehr Test's products and Aehr Test's ability to execute on its business strategy. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's

business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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